



Material Content Data Sheet



Sales Product Name		BC 847C E6327		Issued		28. August 2013		
MA#		MA000962008						
Package		PG-SOT23-3-16		Weight*		8.82 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.003	0.03		332	
	non noble metal	arsenic	7440-38-2	0.000	0.00		3	
	inorganic material	silicon	7440-21-3	0.025	0.28	0.31	2840	3175
leadframe	non noble metal	chromium	7440-47-3	0.008	0.09		933	
	inorganic material	silicon	7440-21-3	0.001	0.01		62	
	non noble metal	titanium	7440-32-6	0.003	0.03		311	
	non noble metal	copper	7440-50-8	2.731	30.95	31.08	309548	310854
wire	noble metal	gold	7440-57-5	0.015	0.17	0.17	1677	1677
encapsulation	organic material	carbon black	1333-86-4	0.058	0.66		6560	
	plastics	brominated resin	-	0.087	0.98		9841	
	inorganic material	antimonytrioxide	1309-64-4	0.116	1.31		13121	
	plastics	epoxy resin	-	1.244	14.10		141048	
	inorganic material	silicondioxide	60676-86-0	4.283	48.56	65.61	485468	656038
leadfinish	non noble metal	tin	7440-31-5	0.150	1.70	1.70	16963	16963
plating	noble metal	silver	7440-22-4	0.100	1.13	1.13	11293	11293
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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